Specifications

Features

1. The infrared sensor is used to detect the surface temperature of BGA. So the closed-loop control and the even heat distribution is realized.

2. The PL part of the infrared BGA rework station is designed with dichromatic vision alignment, which realizes the good coordination of the solder ball and the pad.

3. The machine is connected with PC via IRSoft to record and analyze the operating process, and form the curve.

Specifications
IR

Power	2600W (Max.)
Bottom Preheating Power	1600W (400W×4, dark infrared heater)
	2000W (500W×4, high infrared heating tube, optional)
Power of Top Heater	720W (120W×6, infrared heating tube, wave length: 2-8μm)
Range of Top Heating Area	20-60mm (X, Y adjustable)
Bottom Preheating Area	290×290mm
Max. PCB Size	400×400mm
Communication	USB (Connected with PC)
Temperature Sensor	Non-contact infrared sensor
Weight	About 55kg
Dimension	850(L)×650(W)×730(H)mm

PL

Camera	22×10 times magnifying; 12V/300mA; Horizontal resolution: 480 lines; PAL format
Prism Size	50mm×50mm
BGA Size Range	2×2-60×60(mm)
Video Output Signal	Video signal

RPC

RPC	22×10 times magnifying
	Horizontal resolution: 480 lines
	PAL format